LNJ216C82RA

Hight Bright Surface Mounting Chip LED

Microlens Type

■ Lighting Color

• Red

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	–30 to +85	°C
Storage temperature	T_{stg}	–40 to +100	°C

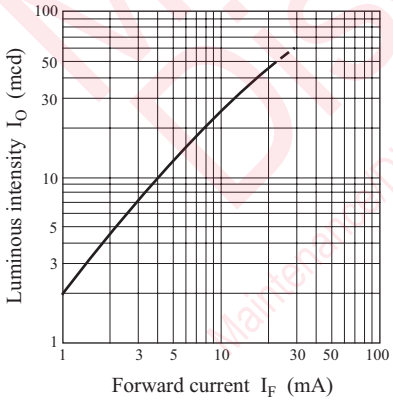
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics T_a = 25°C±3°C

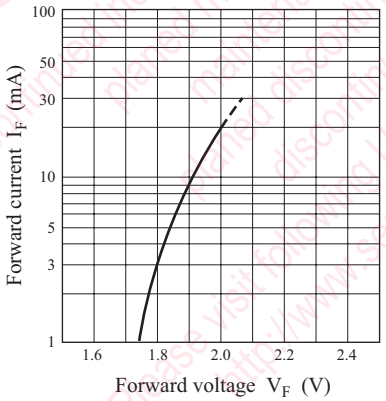
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	I_F = 10 mA	12.8	24.0		mcd
Reverse current	I_R	V_R = 4 V			100	μA
Forward voltage	V_F	I_F = 10 mA		1.92	2.5	V
Peak emission wavelength	λ_P	I_F = 10 mA		645		nm
Spectral half band width	$\Delta\lambda$	I_F = 10 mA		22		nm

Note) *: Measurement tolerance: ±20%

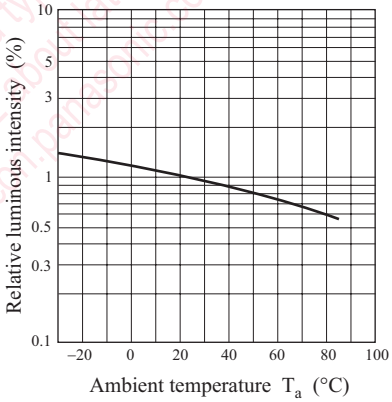
I_O — I_F



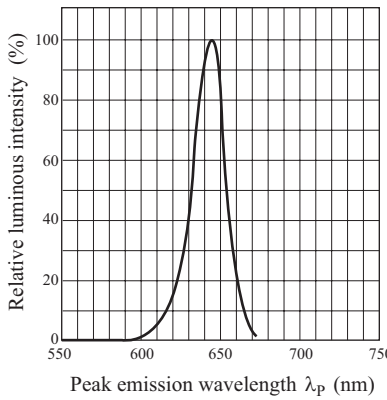
I_F — V_F



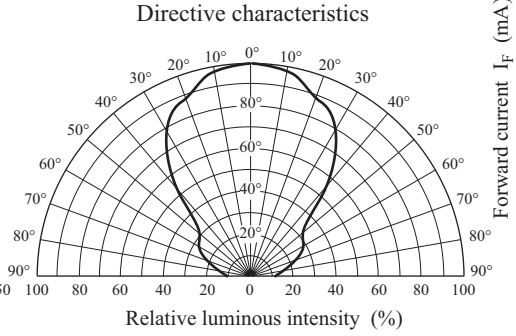
Relative luminous intensity — T_a



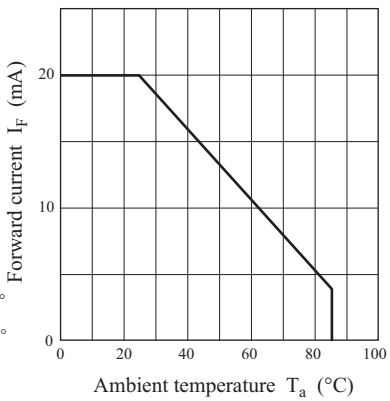
Relative luminous intensity — λ_P



Directive characteristics

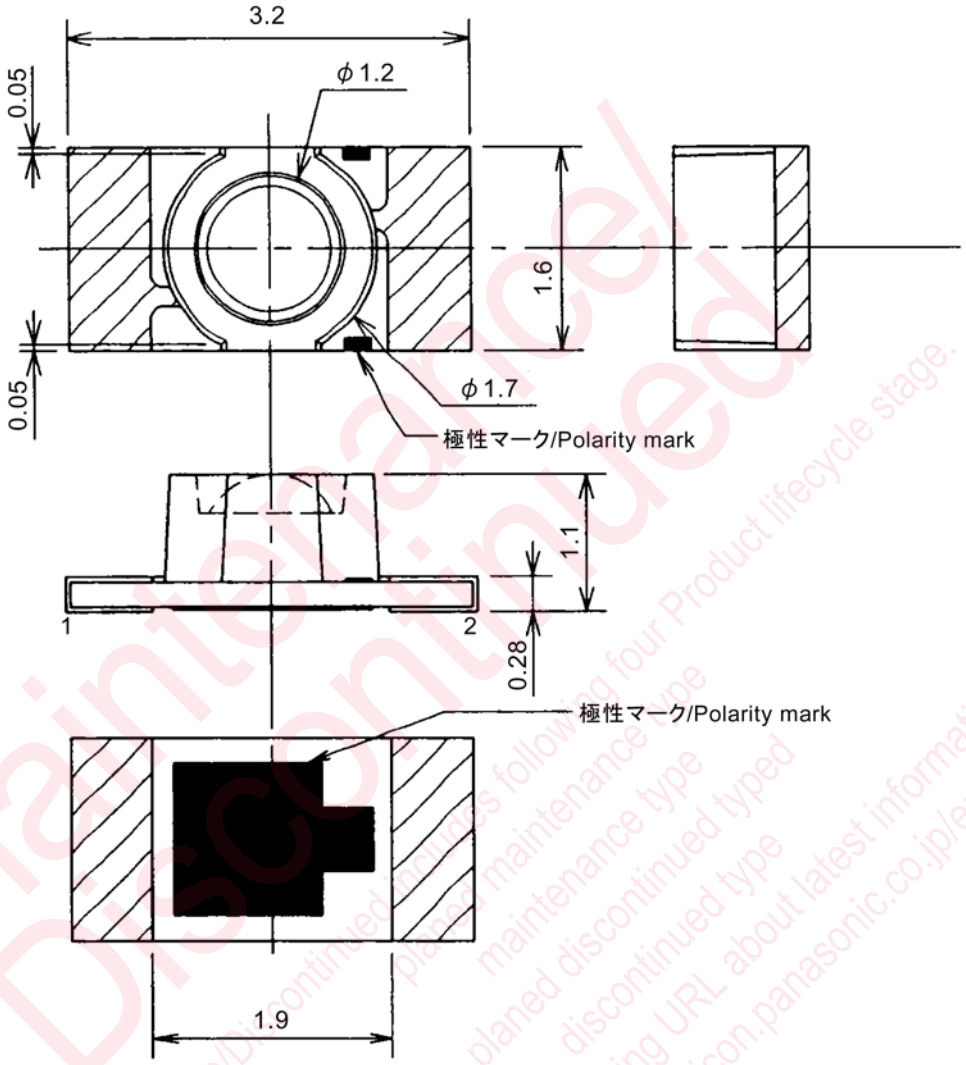


I_F — T_a



■ Package (Unit: mm)

KLTLTN2K1600



- Pin name
  1: Anode
  2: Cathode

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(6) Comply with the instructions for use in order to prevent breakdown and characteristics change due to external factors (ESD, EOS, thermal stress and mechanical stress) at the time of handling, mounting or at customer's process. When using products for which damp-proof packing is required, satisfy the conditions, such as shelf life and the elapsed time since first opening the packages.

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